

U.S. UTILITY Patent Application

**PATENT NUMBER and
ISSUE DATE**

APPL NUM 10079517	FILING DATE 02/22/2002	CLASS 148	SUBCLASS 525	GAU 1742	EXAMINER Wyszomierski
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****APPLICANTS:** Ngo Minh;

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB	DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO 50432-234
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	
Verified and Acknowledged Examiners's initials			
TITLE : Method of forming nitride capped Cu lines with improved adhesion and reduced electromigration along the Cu/nitride interface			

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-54)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
Assistant Examiner		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
Primary Examiner		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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